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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	72 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6.25V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c57t-lp-ss

TABLE 3-2: PINOUT DESCRIPTION - PIC16C55, PIC16C57, PIC16CR57

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	DIP	SOIC	SSOP			
RA0	6	6	5	I/O	TTL	Bi-directional I/O port
RA1	7	7	6	I/O	TTL	
RA2	8	8	7	I/O	TTL	
RA3	9	9	8	I/O	TTL	
RB0	10	10	9	I/O	TTL	Bi-directional I/O port
RB1	11	11	10	I/O	TTL	
RB2	12	12	11	I/O	TTL	
RB3	13	13	12	I/O	TTL	
RB4	14	14	13	I/O	TTL	
RB5	15	15	15	I/O	TTL	
RB6	16	16	16	I/O	TTL	
RB7	17	17	17	I/O	TTL	
RC0	18	18	18	I/O	TTL	Bi-directional I/O port
RC1	19	19	19	I/O	TTL	
RC2	20	20	20	I/O	TTL	
RC3	21	21	21	I/O	TTL	
RC4	22	22	22	I/O	TTL	
RC5	23	23	23	I/O	TTL	
RC6	24	24	24	I/O	TTL	
RC7	25	25	25	I/O	TTL	
T0CKI	1	1	2	I	ST	Clock input to Timer0. Must be tied to V_{SS} or V_{DD}, if not in use, to reduce current consumption.
$\overline{MCLR}$	28	28	28	I	ST	Master clear (RESET) input. This pin is an active low RESET to the device.
OSC1/CLKIN	27	27	27	I	ST	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	26	26	26	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
V_{DD}	2	2	3,4	P	—	Positive supply for logic and I/O pins.
V_{SS}	4	4	1,14	P	—	Ground reference for logic and I/O pins.
N/C	3,5	3,5	—	—	—	Unused, do not connect.

Legend: I = input, O = output, I/O = input/output, P = power, — = Not Used, TTL = TTL input, ST = Schmitt Trigger input

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FIGURE 5-3: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO VDD)

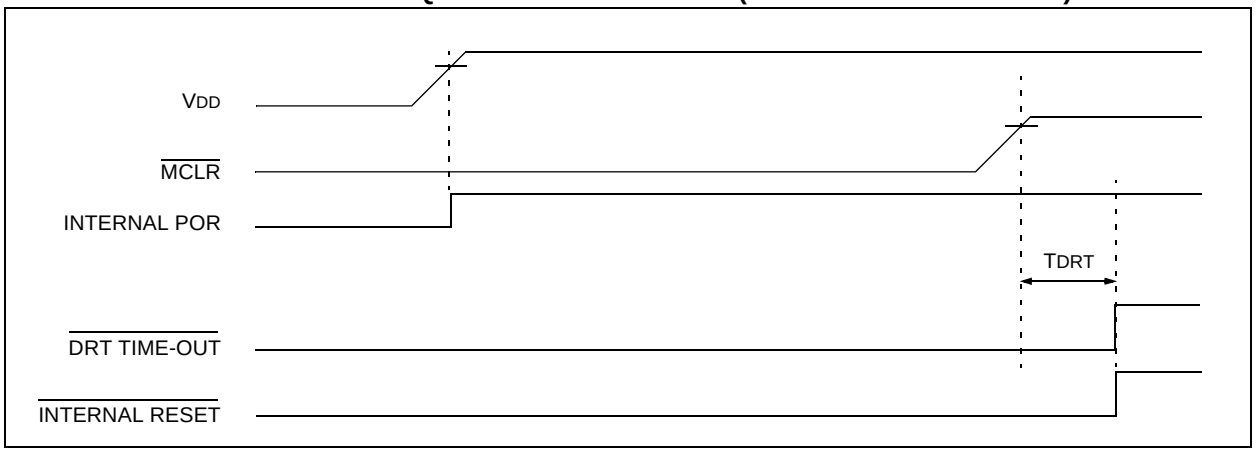


FIGURE 5-4: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO VDD): FAST VDD RISE TIME

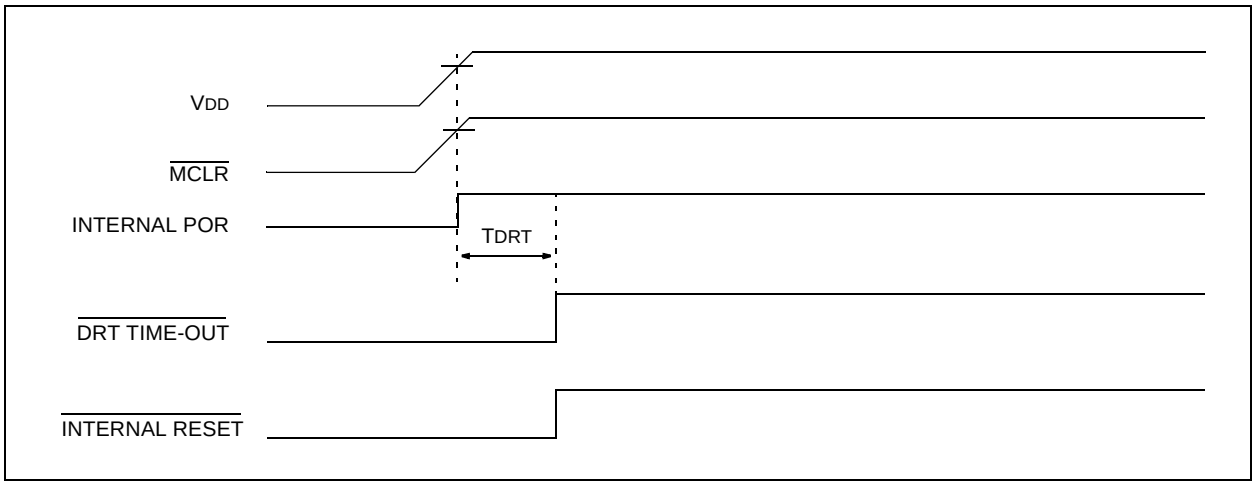
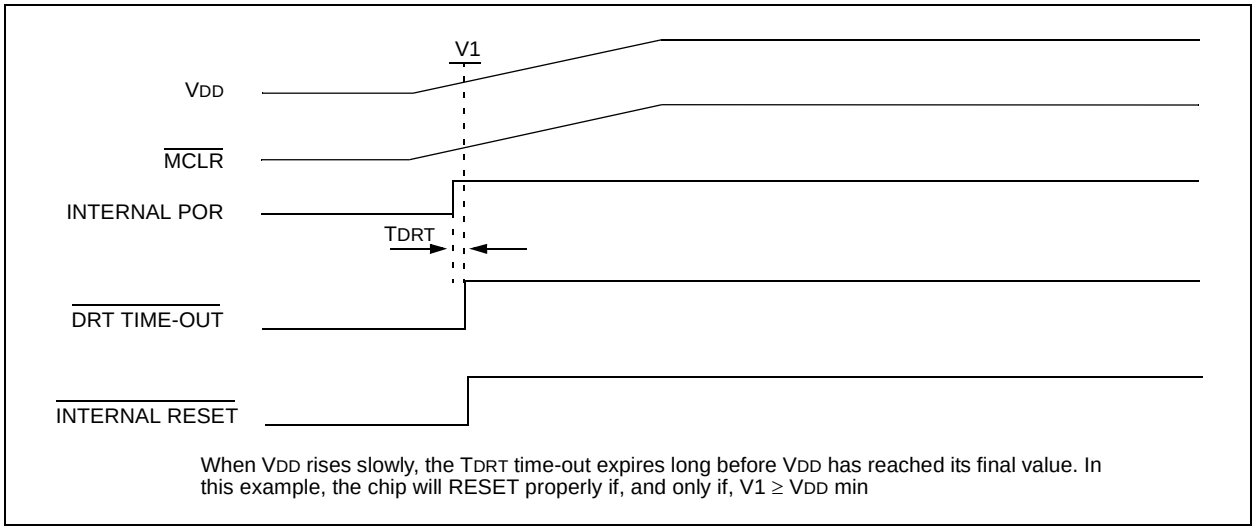


FIGURE 5-5: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO VDD): SLOW VDD RISE TIME



When VDD rises slowly, the TDRT time-out expires long before VDD has reached its final value. In this example, the chip will RESET properly if, and only if, V1 ≥ VDD min

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6.3 STATUS Register

This register contains the arithmetic status of the ALU, the RESET status and the page preselect bits for program memories larger than 512 words.

The STATUS Register can be the destination for any instruction, as with any other register. If the STATUS Register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS Register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS Register as `000u u1uu` (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF` and `MOVWF` instructions be used to alter the STATUS Register because these instructions do not affect the Z, DC or C bits from the STATUS Register. For other instructions which do affect STATUS Bits, see Section 10.0, Instruction Set Summary.

REGISTER 6-1: STATUS REGISTER (ADDRESS: 03h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
PA2	PA1	PA0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

bit 7: **PA2**: This bit unused at this time.
Use of the PA2 bit as a general purpose read/write bit is not recommended, since this may affect upward compatibility with future products.

bit 6-5: **PA<1:0>**: Program page preselect bits (PIC16C56/CR56)(PIC16C57/CR57)(PIC16C58/CR58)
`00` = Page 0 (000h - 1FFh) - PIC16C56/CR56, PIC16C57/CR57, PIC16C58/CR58
`01` = Page 1 (200h - 3FFh) - PIC16C56/CR56, PIC16C57/CR57, PIC16C58/CR58
`10` = Page 2 (400h - 5FFh) - PIC16C57/CR57, PIC16C58/CR58
`11` = Page 3 (600h - 7FFh) - PIC16C57/CR57, PIC16C58/CR58
Each page is 512 words.
Using the PA<1:0> bits as general purpose read/write bits in devices which do not use them for program page preselect is not recommended since this may affect upward compatibility with future products.

bit 4: **$\overline{TO}$**: Time-out bit
`1` = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
`0` = A WDT time-out occurred

bit 3: **$\overline{PD}$**: Power-down bit
`1` = After power-up or by the `CLRWDT` instruction
`0` = By execution of the `SLEEP` instruction

bit 2: **Z**: Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1: **DC**: Digit carry/$\overline{borrow}$ bit (for `ADDWF` and `SUBWF` instructions)
ADDWF
`1` = A carry from the 4th low order bit of the result occurred
`0` = A carry from the 4th low order bit of the result did not occur
SUBWF
`1` = A borrow from the 4th low order bit of the result did not occur
`0` = A borrow from the 4th low order bit of the result occurred

bit 0: **C**: Carry/$\overline{borrow}$ bit (for `ADDWF`, `SUBWF` and `RRF`, `RLF` instructions)

ADDWF	SUBWF	RRF or RLF
`1` = A carry occurred	`1` = A borrow did not occur	Loaded with LSb or MSb, respectively
`0` = A carry did not occur	`0` = A borrow occurred	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown

8.0 TIMER0 MODULE AND TMR0 REGISTER

The Timer0 module has the following features:

- 8-bit timer/counter register, TMR0
  - Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
  - Edge select for external clock

Figure 8-1 is a simplified block diagram of the Timer0 module, while Figure 8-2 shows the electrical structure of the Timer0 input.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In Timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If TMR0 register is written, the increment is inhibited for the following two cycles (Figure 8-3 and Figure 8-4). The user can work around this by writing an adjusted value to the TMR0 register.

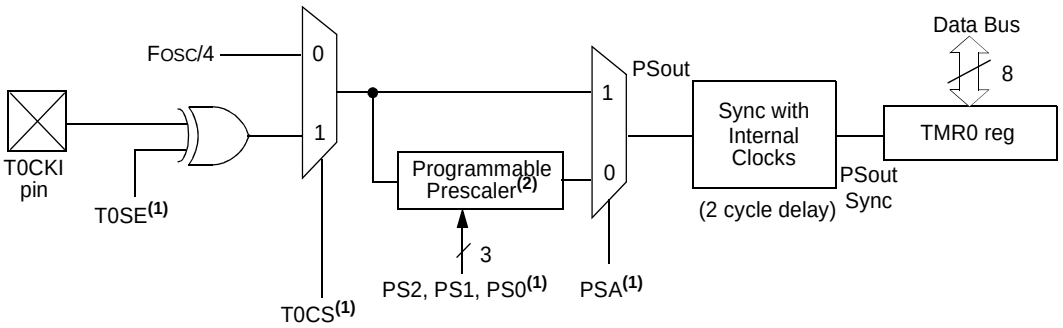
Counter mode is selected by setting the T0CS bit (OPTION<5>). In this mode, Timer0 will increment either on every rising or falling edge of pin T0CKI. The incrementing edge is determined by the source edge select bit T0SE (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 8.1.

Note:	The prescaler may be used by either the Timer0 module or the Watchdog Timer, but not both.

The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4,..., 1:256 are selectable. Section 8.2 details the operation of the prescaler.

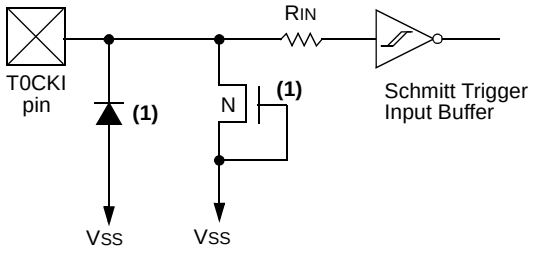
A summary of registers associated with the Timer0 module is found in Table 8-1.

FIGURE 8-1: TIMER0 BLOCK DIAGRAM



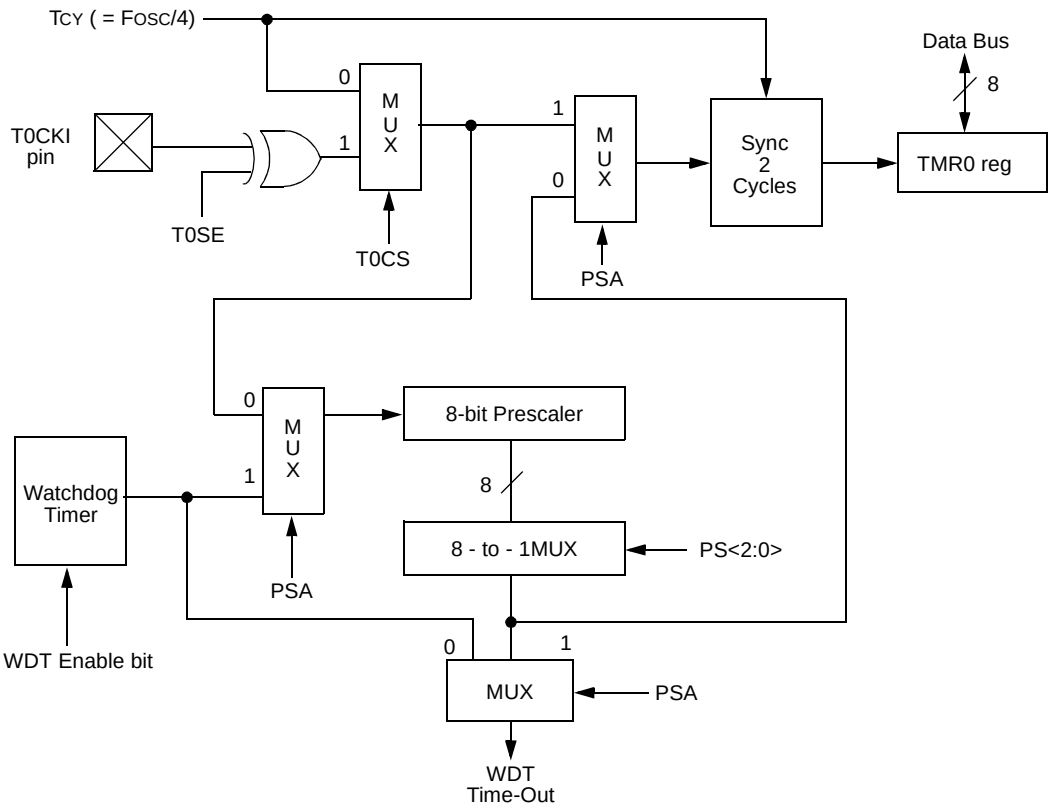
Note 1: Bits T0CS, T0SE, PSA, PS2, PS1 and PS0 are located in the OPTION register (Section 6.4).
2: The prescaler is shared with the Watchdog Timer (Figure 8-6).

FIGURE 8-2: ELECTRICAL STRUCTURE OF T0CKI PIN



Note 1: ESD protection circuits.

FIGURE 8-6: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



Note: T0CS, T0SE, PSA, PS<2:0> are bits in the OPTION register.

10.0 INSTRUCTION SET SUMMARY

Each PIC16C5X instruction is a 12-bit word divided into an OPCODE, which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16C5X instruction set summary in Table 10-2 groups the instructions into byte-oriented, bit-oriented, and literal and control operations. Table 10-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator is used to specify which one of the 32 file registers in that bank is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8 or 9-bit constant or literal value.

TABLE 10-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x1F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0 (store result in W) d = 1 (store result in file register 'f') Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
WDT	Watchdog Timer Counter
$\overline{TO}$	Time-out bit
$\overline{PD}$	Power-down bit
dest	Destination, either the W register or the specified register file location
[ ]	Options
( )	Contents
→	Assigned to
< >	Register bit field
∈	In the set of
italics	User defined term (font is courier)

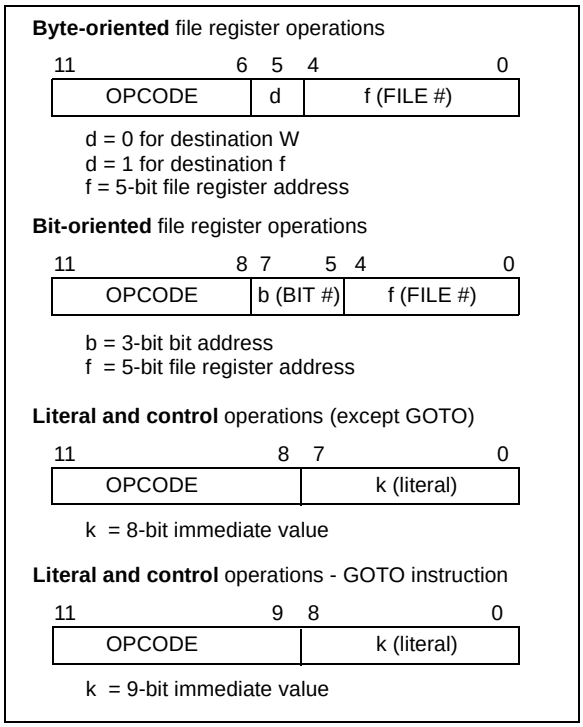
All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time would be 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time would be 2 μs.

Figure 10-1 shows the three general formats that the instructions can have. All examples in the figure use the following format to represent a hexadecimal number:

0xhhh

where 'h' signifies a hexadecimal digit.

FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS



IORLW **Inclusive OR literal with W**

Syntax: [*label*] IORLW k

Operands: $0 \le k \le 255$

Operation: (W) .OR. (k) → (W)

Status Affected: Z

Encoding:

1101	kkkk	kkkk

Description: The contents of the W register are OR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example:
```
IORLW  0x35
```
Before Instruction
W = 0x9A
After Instruction
W = 0xBF
Z = 0

IORWF **Inclusive OR W with f**

Syntax: [*label*] IORWF f,d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (W).OR. (f) → (dest)

Status Affected: Z

Encoding:

0001	00df	ffff

Description: Inclusive OR the W register with register 'f'. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.

Words: 1

Cycles: 1

Example:
```
IORWF          RESULT, 0
```
Before Instruction
RESULT = 0x13
W = 0x91
After Instruction
RESULT = 0x13
W = 0x93
Z = 0

MOVF **Move f**

Syntax: [*label*] MOVF f,d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (f) → (dest)

Status Affected: Z

Encoding:

0010	00df	ffff

Description: The contents of register 'f' is moved to destination 'd'. If 'd' is 0, destination is the W register. If 'd' is 1, the destination is file register 'f'. 'd' is 1 is useful to test a file register since status flag Z is affected.

Words: 1

Cycles: 1

Example:
```
MOVF   FSR,   0
```
After Instruction
W = value in FSR register

MOVLW **Move Literal to W**

Syntax: [*label*] MOVLW k

Operands: $0 \le k \le 255$

Operation: k → (W)

Status Affected: None

Encoding:

1100	kkkk	kkkk

Description: The eight bit literal 'k' is loaded into the W register.

Words: 1

Cycles: 1

Example:
```
MOVLW  0x5A
```
After Instruction
W = 0x5A

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11.8 MPLAB ICD In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD, is a powerful, low cost, run-time development tool. This tool is based on the FLASH PIC MCUs and can be used to develop for this and other PIC microcontrollers. The MPLAB ICD utilizes the in-circuit debugging capability built into the FLASH devices. This feature, along with Microchip's In-Circuit Serial Programming™ protocol, offers cost-effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by watching variables, single-stepping and setting break points. Running at full speed enables testing hardware in real-time.

11.9 PRO MATE II Universal Device Programmer

The PRO MATE II universal device programmer is a full-featured programmer, capable of operating in Stand-alone mode, as well as PC-hosted mode. The PRO MATE II device programmer is CE compliant.

The PRO MATE II device programmer has programmable V_{DD} and V_{PP} supplies, which allow it to verify programmed memory at V_{DD} min and V_{DD} max for maximum reliability. It has an LCD display for instructions and error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In Stand-alone mode, the PRO MATE II device programmer can read, verify, or program PIC devices. It can also set code protection in this mode.

11.10 PICSTART Plus Entry Level Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient.

The PICSTART Plus development programmer supports all PIC devices with up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.

11.11 PICDEM 1 Low Cost PIC MCU Demonstration Board

The PICDEM 1 demonstration board is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The user can program the sample microcontrollers provided with the PICDEM 1 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The user can also connect the PICDEM 1 demonstration board to the MPLAB ICE in-circuit emulator and download the firmware to the emulator for testing. A prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs connected to PORTB.

11.12 PICDEM 2 Low Cost PIC16CXX Demonstration Board

The PICDEM 2 demonstration board is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 2 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a serial EEPROM to demonstrate usage of the I^2C™ bus and separate headers for connection to an LCD module and a keypad.

11.13 PICDEM 3 Low Cost PIC16CXXX Demonstration Board

The PICDEM 3 demonstration board is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with an LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 3 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer with an adapter socket, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 3 demonstration board to test firmware. A prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM 3 demonstration board is a LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM 3 demonstration board provides an additional RS-232 interface and Windows software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

11.14 PICDEM 17 Demonstration Board

The PICDEM 17 demonstration board is an evaluation board that demonstrates the capabilities of several Microchip microcontrollers, including PIC17C752, PIC17C756A, PIC17C762 and PIC17C766. All necessary hardware is included to run basic demo programs, which are supplied on a 3.5-inch disk. A programmed sample is included and the user may erase it and program it with the other sample programs using the PRO MATE II device programmer, or the PICSTART Plus development programmer, and easily debug and test the sample code. In addition, the PICDEM 17 demonstration board supports downloading of programs to and executing out of external FLASH memory on board. The PICDEM 17 demonstration board is also usable with the MPLAB ICE in-circuit emulator, or the PICMASTER emulator and all of the sample programs can be run and modified using either emulator. Additionally, a generous prototype area is available for user hardware.

11.15 KEELOQ Evaluation and Programming Tools

KEELOQ evaluation and programming tools support Microchip's HCS Secure Data Products. The HCS evaluation kit includes a LCD display to show changing codes, a decoder to decode transmissions and a programming interface to program test transmitters.

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12.3 DC Characteristics: PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)

PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)			Standard Operating Conditions (unless otherwise specified) Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**					
		PIC16C5X-RCE	3.25	—	6.0	V	
		PIC16C5X-XTE	3.25	—	6.0	V	
		PIC16C5X-10E	4.5	—	5.5	V	
		PIC16C5X-HSE	4.5	—	5.5	V	
		PIC16C5X-LPE	2.5	—	6.0	V	
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	**Supply Current(2)**					
		PIC16C5X-RCE(3)	—	1.8	3.3	mA	FOSC = 4 MHz, VDD = 5.5V
		PIC16C5X-XTE	—	1.8	3.3	mA	FOSC = 4 MHz, VDD = 5.5V
		PIC16C5X-10E	—	4.8	10	mA	FOSC = 10 MHz, VDD = 5.5V
		PIC16C5X-HSE	—	4.8	10	mA	FOSC = 10 MHz, VDD = 5.5V
		PIC16C5X-HSE	—	9.0	20	mA	FOSC = 16 MHz, VDD = 5.5V
		PIC16C5X-LPE	—	19	55	μA	FOSC = 32 kHz, VDD = 3.25V, WDT disabled
D020	IPD	**Power-down Current(2)**	—	5.0	22	μA	VDD = 3.25V, WDT enabled
			—	0.8	18	μA	VDD = 3.25V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

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13.4 DC Characteristics: PIC16CR54A-04E, 10E, 20E (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D030	VIL	**Input Low Voltage**					
		I/O ports	Vss	—	0.15 VDD	V	Pin at hi-impedance
		MCLR (Schmitt Trigger)	Vss	—	0.15 VDD	V	
		T0CKI (Schmitt Trigger)	Vss	—	0.15 VDD	V	
		OSC1 (Schmitt Trigger)	Vss	—	0.15 VDD	V	RC mode only(3)
		OSC1	Vss	—	0.3 VDD	V	XT, HS and LP modes
D040	VIH	**Input High Voltage**					
		I/O ports	0.45 VDD	—	VDD	V	For all VDD(4)
		I/O ports	2.0	—	VDD	V	4.0V < VDD ≤ 5.5V(4)
		I/O ports	0.36 VDD	—	VDD	V	VDD > 5.5V
		MCLR (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		T0CKI (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		OSC1 (Schmitt Trigger)	0.85 VDD	—	VDD	V	RC mode only(3)
		OSC1	0.7 VDD	—	VDD	V	XT, HS and LP modes
D050	VHYS	**Hysteresis of Schmitt Trigger inputs**	0.15 VDD*	—	—	V	
D060	IIL	**Input Leakage Current(1,2)**					**For VDD ≤ 5.5V:**
		I/O ports	–1.0	0.5	+1.0	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
		MCLR	–5.0	—	—	µA	VPIN = VSS + 0.25V
		MCLR	—	0.5	+5.0	µA	VPIN = VDD
		T0CKI	–3.0	0.5	+3.0	µA	VSS ≤ VPIN ≤ VDD
		OSC1	–3.0	0.5	+3.0	µA	VSS ≤ VPIN ≤ VDD, XT, HS and LP modes
D080	VOL	**Output Low Voltage**					
		I/O ports	—	—	0.6	V	IOL = 8.7 mA, VDD = 4.5V
		OSC2/CLKOUT	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, RC mode only
D090	VOH	**Output High Voltage(2)**					
		I/O ports	VDD – 0.7	—	—	V	IOH = –5.4 mA, VDD = 4.5V
		OSC2/CLKOUT	VDD – 0.7	—	—	V	IOH = –1.0 mA, VDD = 4.5V, RC mode only

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

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15.2 DC Characteristics: PIC16C54A-04E, 10E, 20E (Extended) PIC16LC54A-04E (Extended)

PIC16LC54A-04E (Extended)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
PIC16C54A-04E, 10E, 20E (Extended)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		PIC16LC54A	3.0 2.5	— —	6.25 6.25	V V	XT and RC modes LP mode
D001A		PIC16C54A	3.5 4.5	— —	5.5 5.5	V V	RC and XT modes HS mode
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
	IDD	**Supply Current(2)**					
D010		PIC16LC54A	—	0.5	25	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC(3) and XT modes
			—	11	27	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Commercial
			—	11	35	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Industrial
			—	11	37	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Extended
D010A		PIC16C54A	—	1.8	3.3	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC(3) and XT modes
			—	4.8	10	mA	FOSC = 10 MHz, VDD = 5.5V, HS mode
			—	9.0	20	mA	FOSC = 20 MHz, VDD = 5.5V, HS mode

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

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TABLE 15-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54A

AC Characteristics	Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –20°C ≤ TA ≤ +85°C for industrial - PIC16LV54A-02I –40°C ≤ TA ≤ +125°C for extended						
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
1	TOSC	External CLKIN Period(1)	250	—	—	ns	XT OSC mode
			500	—	—	ns	XT OSC mode (PIC16LV54A)
			250	—	—	ns	HS OSC mode (04)
			100	—	—	ns	HS OSC mode (10)
			50	—	—	ns	HS OSC mode (20)
			5.0	—	—	µs	LP OSC mode
		Oscillator Period(1)	250	—	—	ns	RC OSC mode
			500	—	—	ns	RC OSC mode (PIC16LV54A)
			250	—	10,000	ns	XT OSC mode
			500	—	—	ns	XT OSC mode (PIC16LV54A)
			250	—	250	ns	HS OSC mode (04)
			100	—	250	ns	HS OSC mode (10)
			50	—	250	ns	HS OSC mode (20)
			5.0	—	200	µs	LP OSC mode
2	Tcy	Instruction Cycle Time(2)	—	4/FOSC	—	—	
3	TosL, TosH	Clock in (OSC1) Low or High Time	85*	—	—	ns	XT oscillator
			20*	—	—	ns	HS oscillator
			2.0*	—	—	µs	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	—	—	25*	ns	XT oscillator
			—	—	25*	ns	HS oscillator
			—	—	50*	ns	LP oscillator

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.
When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

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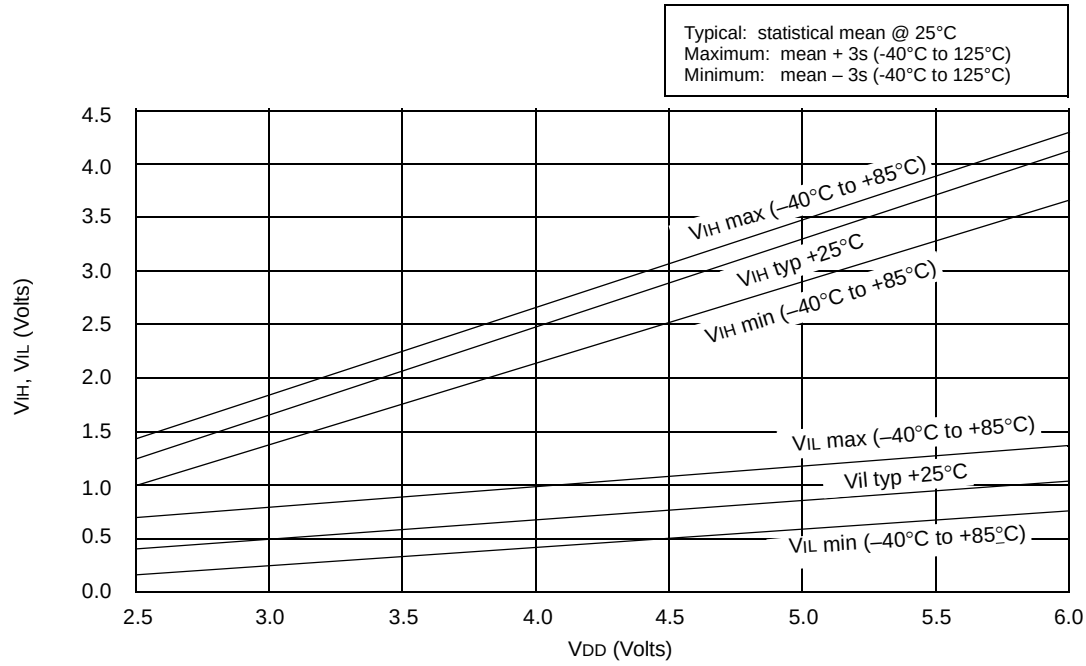
FIGURE 16-9: VIH, VIL OF $\overline{\text{MCLR}}$, T0CKI AND OSC1 (IN RC MODE) vs. VDD



Note: These input pins have Schmitt Trigger input buffers.

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FIGURE 16-10: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 pF, 25°C)

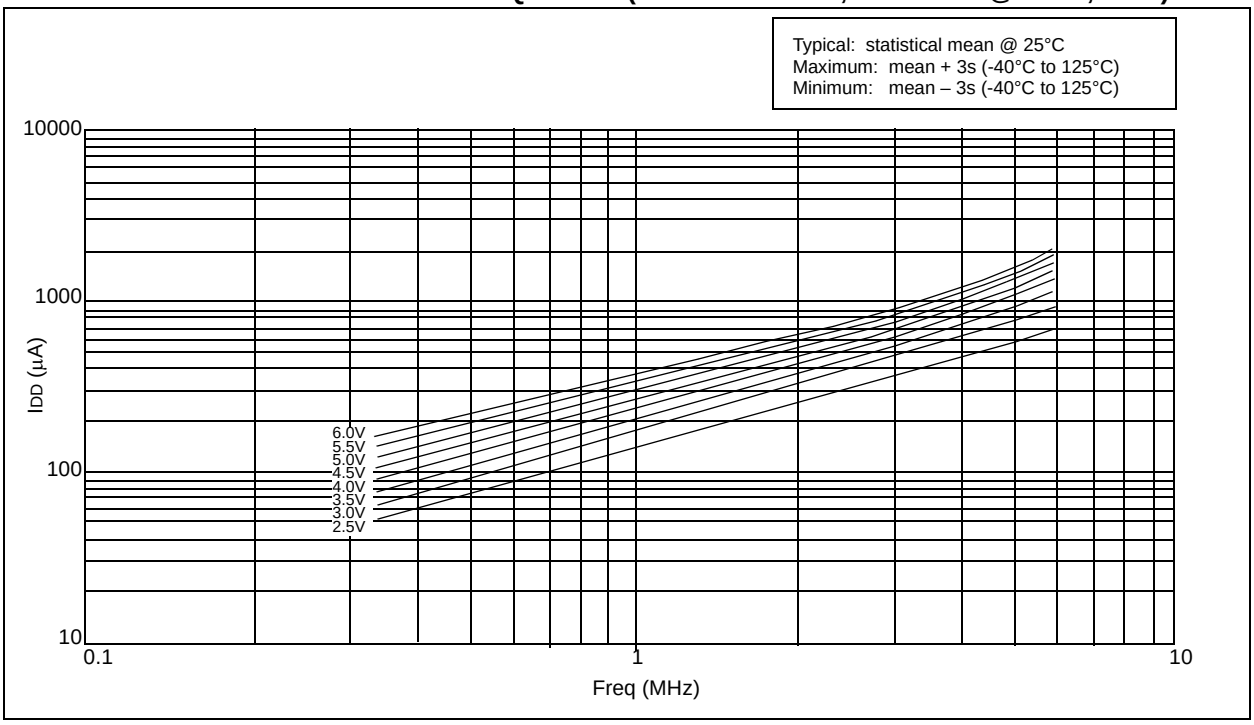


FIGURE 16-11: MAXIMUM IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 pF, –40°C to +85°C)

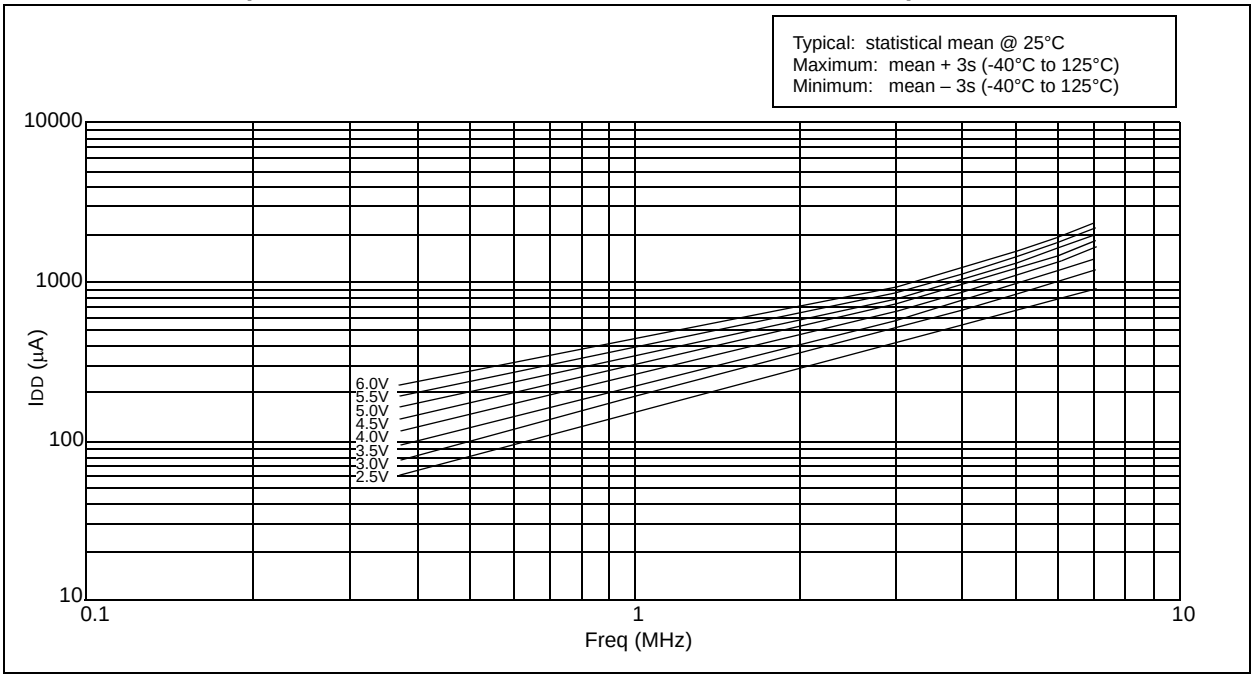
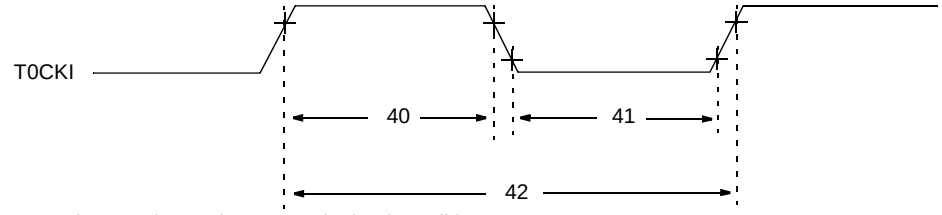


FIGURE 17-9: TIMER0 CLOCK TIMINGS - PIC16C5X, PIC16CR5X



Note: Please refer to Figure 17-5 for load conditions.

TABLE 17-4: TIMER0 CLOCK REQUIREMENTS - PIC16C5X, PIC16CR5X

AC Characteristics			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
40	Tt0H	T0CKI High Pulse Width - No Prescaler	0.5 TCY + 20*	—	—	ns	
		- With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width - No Prescaler	0.5 TCY + 20*	—	—	ns	
		- With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period	20 or $\frac{T_{CY} + 40}{N}$*	—	—	ns	Whichever is greater. N = Prescale Value (1, 2, 4,..., 256)

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 18-2: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 20 pF, 25°C

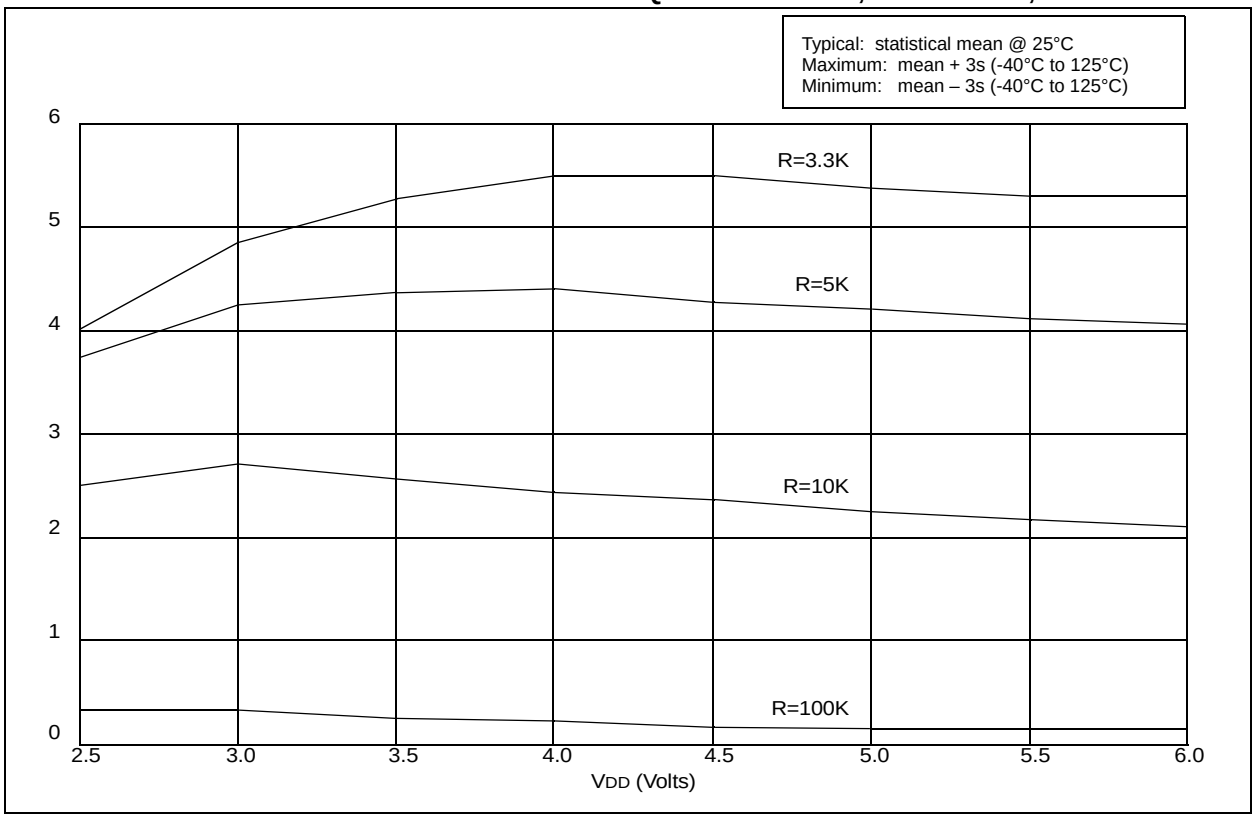

FIGURE 18-3: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 100 pF, 25°C

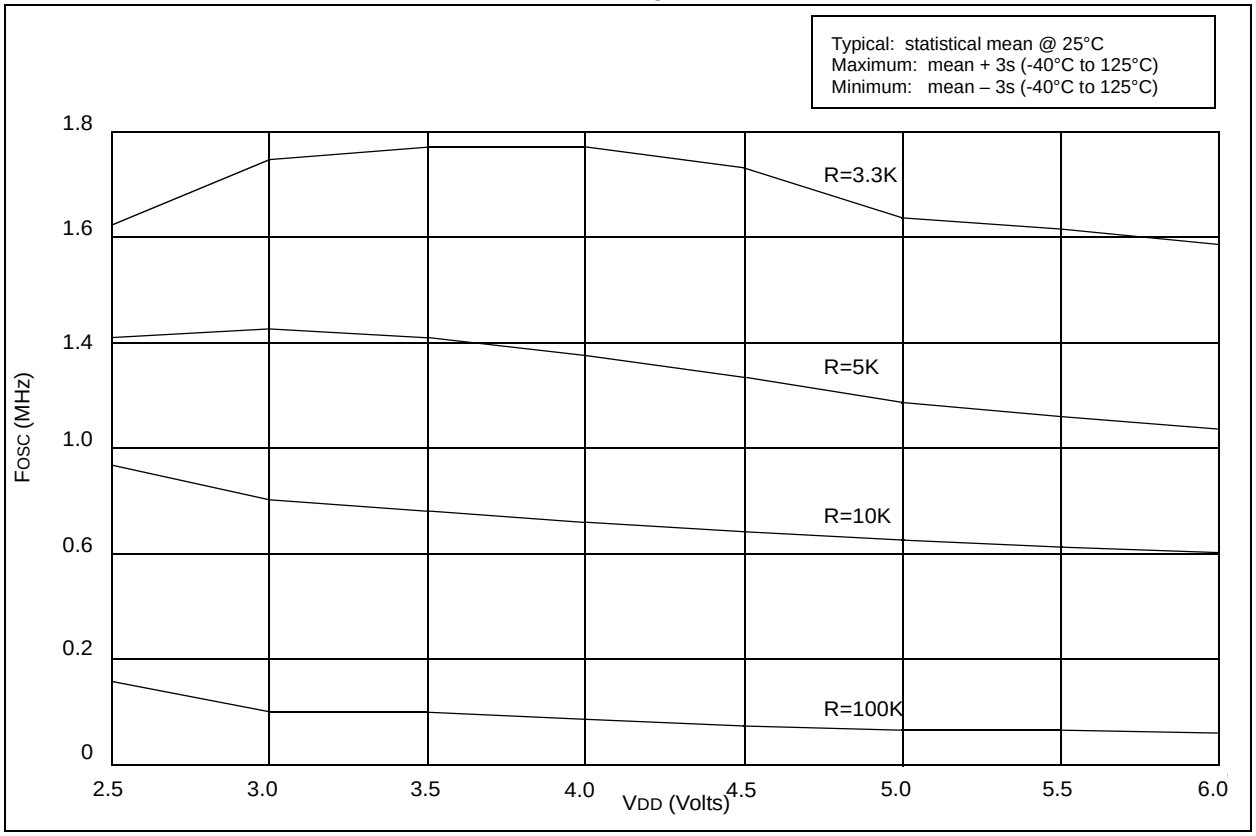

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FIGURE 18-12: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 100 pF, 25°C)

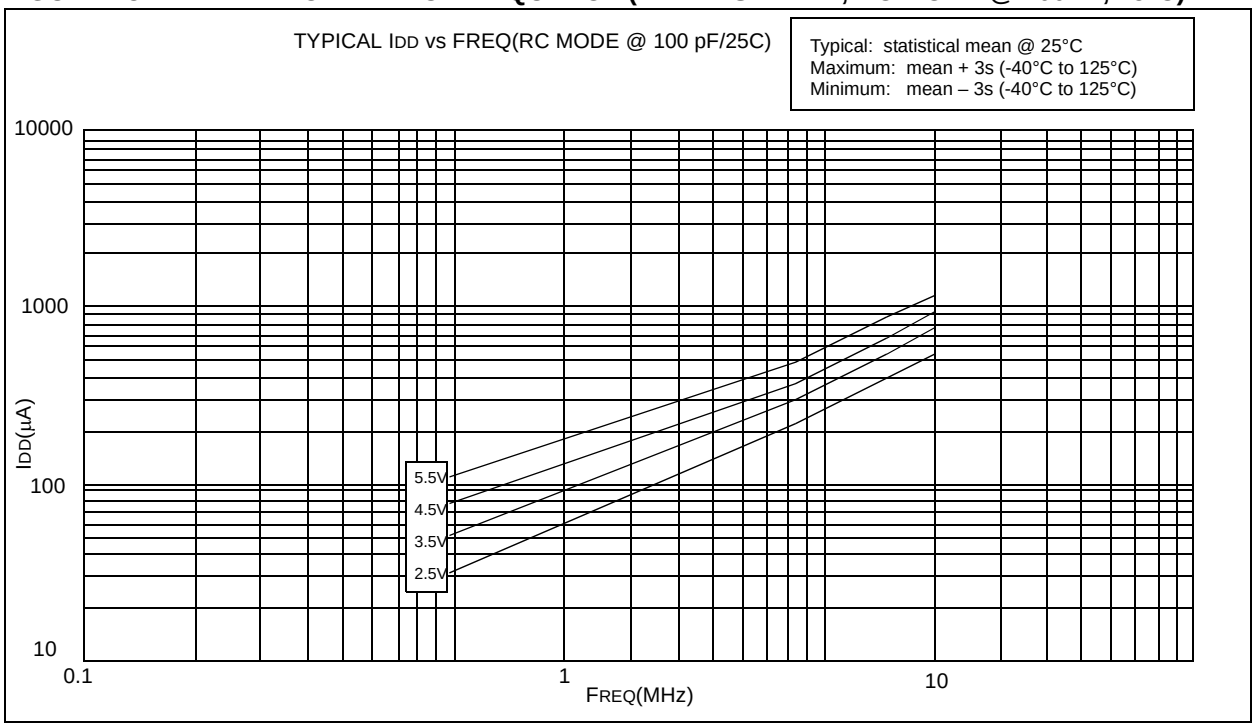
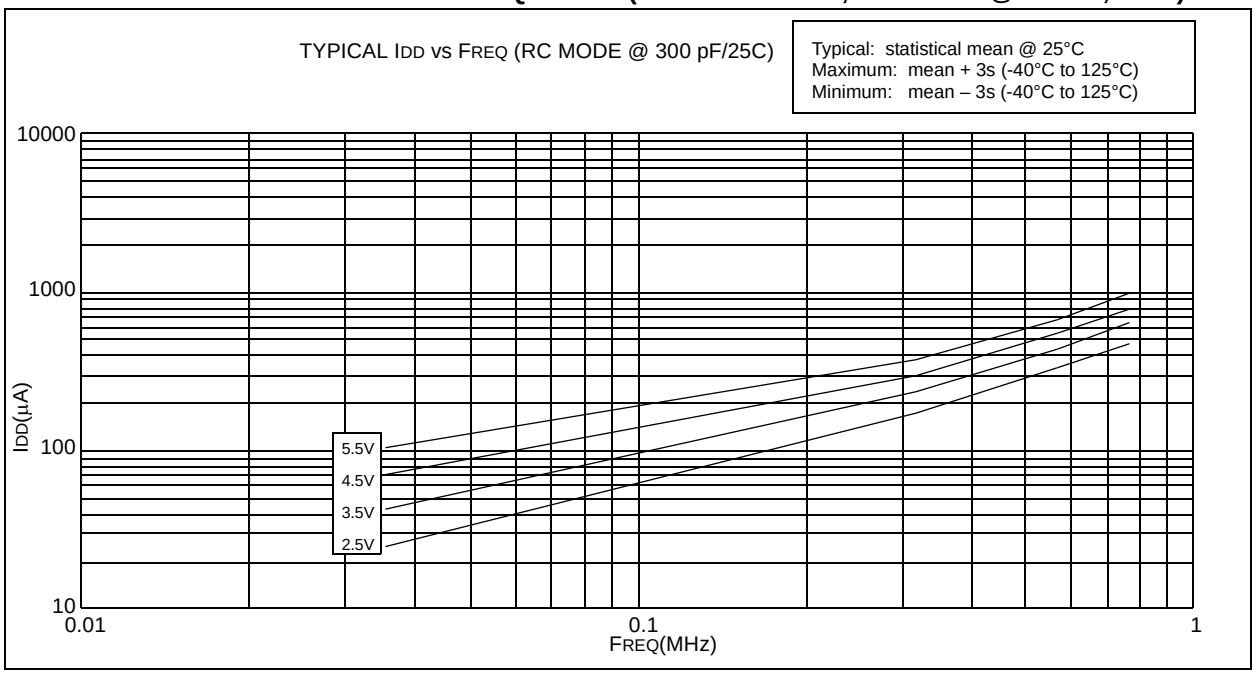
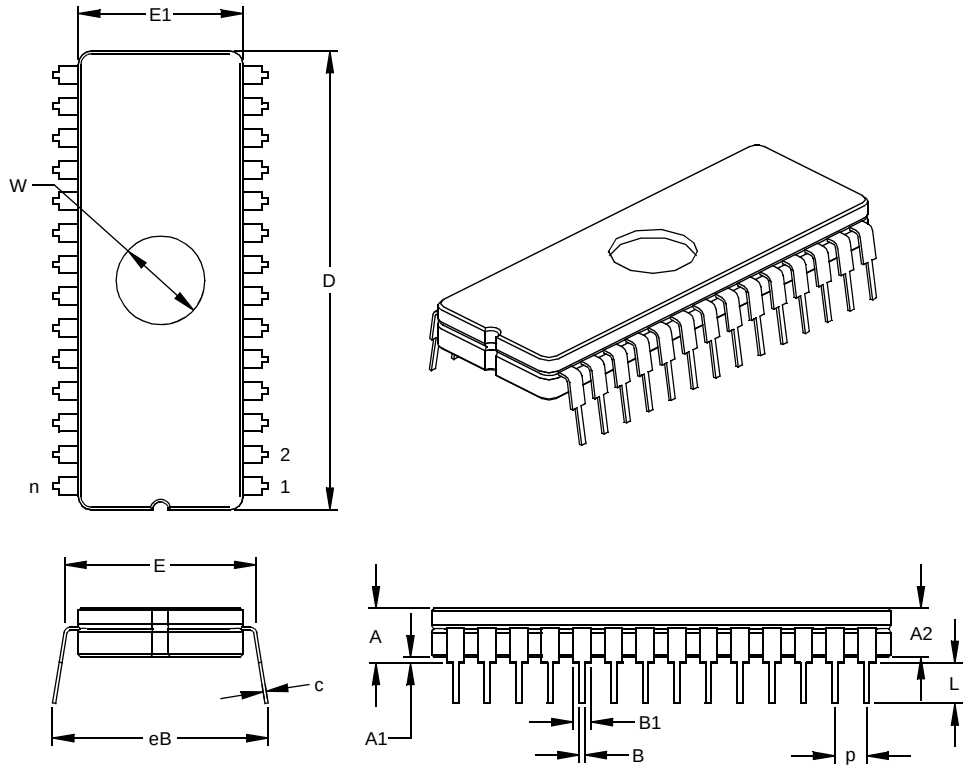


FIGURE 18-13: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 pF, 25°C)



28-Lead Ceramic Dual In-line with Window (JW) – 600 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.195	.210	.225	4.95	5.33	5.72
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.038	.060	0.38	0.95	1.52
Shoulder to Shoulder Width	E	.595	.600	.625	15.11	15.24	15.88
Ceramic Pkg. Width	E1	.514	.520	.526	13.06	13.21	13.36
Overall Length	D	1.430	1.460	1.490	36.32	37.08	37.85
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.058	.065	1.27	1.46	1.65
Lower Lead Width	B	.016	.020	.023	0.41	0.51	0.58
Overall Row Spacing §	eB	.610	.660	.710	15.49	16.76	18.03
Window Diameter	W	.270	.280	.290	6.86	7.11	7.37

* Controlling Parameter
§ Significant Characteristic
JEDEC Equivalent: MO-103
Drawing No. C04-013

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